



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-03-12
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SCT055H65G3-7	T38P*BRF5VV2	A	SH1A	2025-03-12
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1540	mg	Each	ECOPACK® 1
<b>Identity</b>	<b>Authority</b>			
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	245	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
NAC	10.2x9.15	7	nac
Comment			
Comment	A08P H2PAK-7		

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
<b>Exemption Id.</b>	<b>Description</b>
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
<b>Substance</b>	<b>amount in product (mg)</b>	<b>Application</b>	<b>ppm in product</b>
Nickel	1.207	alloy	784
Lead	1.954	solder	1269

QueryList :Customer	Response
<b>QUERY</b>	<b>Response</b>

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
<b>QUERY</b>	<b>Response</b>			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	true			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
<b>Hazardous substance</b>				
<b>Lead (Pb)</b>	<b>Cadmium (Cd)</b>	<b>Mercury (Hg)</b>	<b>Hexavalent Chromium (Cr VI)</b>	<b>PBB &amp; PBDE</b>
X	O	O	O	O

QueryList : REACH-21st January 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	false			
<b>CategoryLevel_Name</b>	<b>CategoryLevel_Threshold</b>	<b>amount in product (mg)</b>	<b>Application</b>	<b>ppm in product</b>
Lead (Pb)	1000 ppm	1.95	Soft solder	1269
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
<b>CategoryLevel_Name</b>	<b>CategoryLevel_Threshold</b>	<b>Amount in embedded article / Homogeneous material (mg)</b>	<b>Application - article / Homogeneous material</b>	<b>ppm in article /Homogeneous material</b>
Lead dinitrate	1000 ppm	1.954	Soft solder	955034



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	<b>Tin,</b>

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	true

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T38P*BRF5VV2		1540.0000		5000001.0	1000001.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	3.390	mg	supplier	die	Silicon(Si)	7440-21-3		0.014	mg	4130	9
	M-011 Other inorganic materials			California 65	die	Silicium carbide	409-21-2		3.177	mg	937168	2063
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.058	mg	17109	38
				supplier	metallisation	Copper(Cu)	7440-50-8		0.008	mg	2360	5
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.050	mg	14749	32
				supplier	metallisation	Silver(Ag)	7440-22-4		0.051	mg	15044	33
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.006	mg	1770	4
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	590	1
				supplier	Passivation	Silicon nitride(S	12033-89-5		0.009	mg	2655	6
				supplier	passivation	Silicon oxide	7631-86-9		0.015	mg	4425	10
Leadframe	M-004 Copper and its alloys	1032.283	mg	supplier	alloy	Copper(Cu)	7440-50-8		1029.762	mg	997558	668677
				supplier	alloy	Iron phosphide	26508-33-8		0.866	mg	839	562
				supplier	alloy	Iron(Fe)	7439-89-6		0.474	mg	459	308
				supplier	metallization	Nickel(Ni)	7440-02-0		1.157	mg	1121	751
				supplier	metallization	Phosphorus me	7723-14-0		0.024	mg	23	16
Soft solder	Solder	2.046	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	1.954	mg	955034	1269
				supplier	solder	Silver(Ag)	7440-22-4		0.051	mg	24927	33
				supplier	solder	Tin(Sn)	7440-31-5		0.041	mg	20039	27
Encapsulation	M-011 Other inorganic materials	500.005	mg	supplier	mold compound	Silica vitreous	60676-86-0		430.005	mg	860001	279224
				supplier	mold compound	Epoxy Cresol N	29690-82-2		12.500	mg	25000	8117
				supplier	mold compound	Phenol resin	1985-51-9		20.000	mg	40000	12987
				supplier	mold compound	Biphenyl epoxy	85954-11-6		5.000	mg	10000	3247
				supplier	mold compound	Antimony trioxid	proprietary		20.000	mg	40000	12987
				supplier	mold compound	Brominated Epc	40039-93-8		10.000	mg	20000	6494
				supplier	mold compound	Carbon black	1333-86-4		2.500	mg	5000	1623
Connections coating	Solder	2.276	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		2.276	mg	1000000	1478